

# MC74HCT14A

## Hex Schmitt-Trigger Inverter with LSTTL Compatible Inputs

### High-Performance Silicon-Gate CMOS

The MC74HCT14A may be used as a level converter for interfacing TTL or NMOS outputs to high-speed CMOS inputs.

The HCT14A is useful to “square up” slow input rise and fall times. Due to the hysteresis voltage of the Schmitt trigger, the HCT14A finds applications in noisy environments.

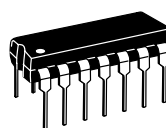
- Output Drive Capability: 10 LSTTL Loads
- TTL/NMOS-Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: 1.0  $\mu$ A
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 72 FETs or 18 Equivalent Gates



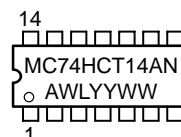
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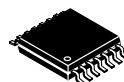
#### MARKING DIAGRAMS



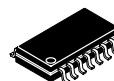
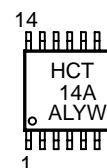
PDIP-14  
N SUFFIX  
CASE 646



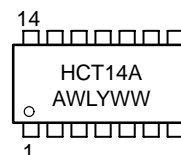
SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



EIAJ-14  
F SUFFIX  
CASE 965

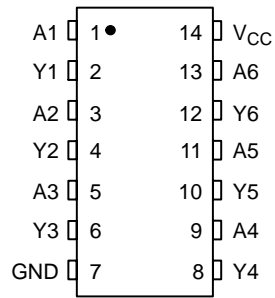


A = Assembly Location  
L, WL = Wafer Lot  
Y, YY = Year  
W, WW = Work Week

#### ORDERING INFORMATION

Device	Package	Shipping
MC74HCT14AN	PDIP-14	2000/Box
MC74HCT14AD	SOIC-14	55/Rail
MC74HCT14ADR2	SOIC-14	2500/Reel
MC74HCT14ADTR2	TSSOP-14	2000/Reel
MC74HCT14AFEL	EIAJ-14	2000/Reel

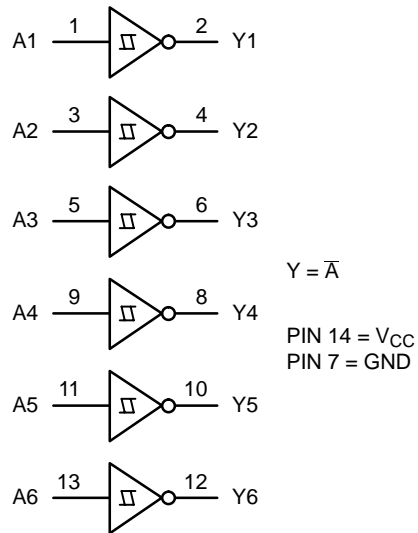
# MC74HCT14A



**FUNCTION TABLE**

Input A	Output Y
L	H
H	L

**Figure 1. Pin Assignment**



**Figure 2. Logic Diagram**

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## MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>I</sub>	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>O</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	±20	mA
I <sub>OK</sub>	DC Output Diode Current	±25	mA
I <sub>O</sub>	DC Output Sink Current	±25	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±50	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±50	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T <sub>J</sub>	Junction Temperature under Bias	+150	°C
θ <sub>JA</sub>	Thermal Resistance	PDIP SOIC TSSOP 78 125 170	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	PDIP SOIC TSSOP 750 500 450	mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 30% - 35%	UL-94-VO (0.125 in)	
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>4000 >300 >1000	V
I <sub>Latch-Up</sub>	Latch-Up Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 5)	±300	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum-rated conditions is not implied.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA/JESD78.
6. For high frequency or heavy load considerations, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V <sub>I</sub> , V <sub>O</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types	-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Figure 3)	—	(Note 7)	ns

7. No Limit when V<sub>I</sub> ≈ 50% V<sub>CC</sub>, I<sub>CC</sub> > 1 mA.
8. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

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## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> Volts	Temperature Limit						Unit
				-55°C to 25°C		≤ 85°C		≤ 125°C		
				Min	Max	Min	Max	Min	Max	
V <sub>T+</sub> max	Maximum Positive-Going Input Threshold Voltage	V <sub>O</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5		1.9 2.1		1.9 2.1		1.9 2.1	V
V <sub>T+</sub> min	Minimum Positive-Going Input Threshold Voltage	V <sub>O</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	1.2 1.4		1.2 1.4		1.2 1.4		V
V <sub>T-</sub> max	Maximum Negative-Going Input Threshold Voltage	V <sub>O</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5		1.2 1.4		1.2 1.4		1.2 1.4	
V <sub>T-</sub> min	Minimum Negative-Going Input Threshold Voltage	V <sub>O</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	0.5 0.6		0.5 0.6		0.5 0.6		
V <sub>H</sub> max	Maximum Hysteresis Voltage	V <sub>O</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5		1.4 1.5		1.4 1.5		1.4 1.5	
V <sub>H</sub> min	Minimum Hysteresis Voltage	V <sub>O</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	0.4 0.4		0.4 0.4		0.4 0.4		
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>I</sub> < V <sub>T-</sub> min  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	4.4 5.4		4.4 5.4		4.4 5.4		V
		V <sub>I</sub> < V <sub>T-</sub> min  I <sub>out</sub>   ≤ 4.0 mA	4.5	3.98		3.84		3.7		
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>I</sub> ≥ V <sub>T+</sub> max  I <sub>out</sub>   ≤ 20 μA	4.5 5.5		0.1 0.1		0.1 0.1		0.1 0.1	V
		V <sub>I</sub> ≥ V <sub>T+</sub> max  I <sub>out</sub>   ≤ 4.0 mA	4.5		0.26		0.33		0.4	
I <sub>IK</sub>	Maximum Input Leakage Current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5		±0.1		±1.0		±1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per package)	V <sub>I</sub> = V <sub>CC</sub> or GND I <sub>out</sub> = 0 μA	5.5		1.0		10		40	μA
ΔI <sub>CC</sub>	Additional Quiescent Supply Current	V <sub>I</sub> = 2.4 V, Any One Input V <sub>I</sub> = V <sub>CC</sub> or GND, Other Inputs I <sub>out</sub> = 0 μA	5.5	≥ -55°C		25°C to 125°C				mA
				2.9		2.4				

9. Information on typical parametric values can be found in the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

## AC CHARACTERISTICS (C<sub>L</sub> = 50 pF; Input t<sub>r</sub> = t<sub>f</sub> = 6.0 ns)

Symbol	Parameter	Test Conditions	Figures	Guaranteed Limit						Unit
				-55°C to 25°C		≤ 85°C		≤ 125°C		
				Min	Max	Min	Max	Min	Max	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Input A to Output Y (L to H)	V <sub>CC</sub> = 5.0 V ± 10% C <sub>L</sub> = 50 pF, Input t <sub>r</sub> = t <sub>f</sub> = 6.0 ns	3 & 4		32		40		48	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output	V <sub>CC</sub> = 5.0 V ± 10% C <sub>L</sub> = 50 pF, Input t <sub>r</sub> = t <sub>f</sub> = 6.0 ns	3 & 4		15		19		22	ns

10. For propagation delays with loads other than 50 pF, and information on typical parametric values, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

C <sub>PD</sub>	Power Dissipation Capacitance, per Inverter (Note 11)	Typical @ 25°C, V <sub>CC</sub> = 5.0 V		pF
		32		

11. Used to determine the no-load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup>f + I<sub>CC</sub> V<sub>CC</sub>. For load considerations, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

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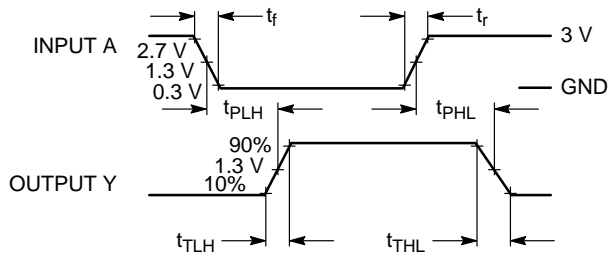
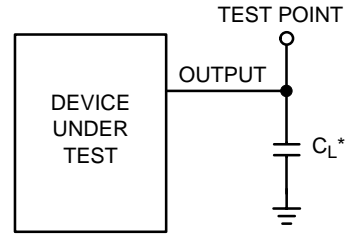


Figure 3. Switching Waveforms



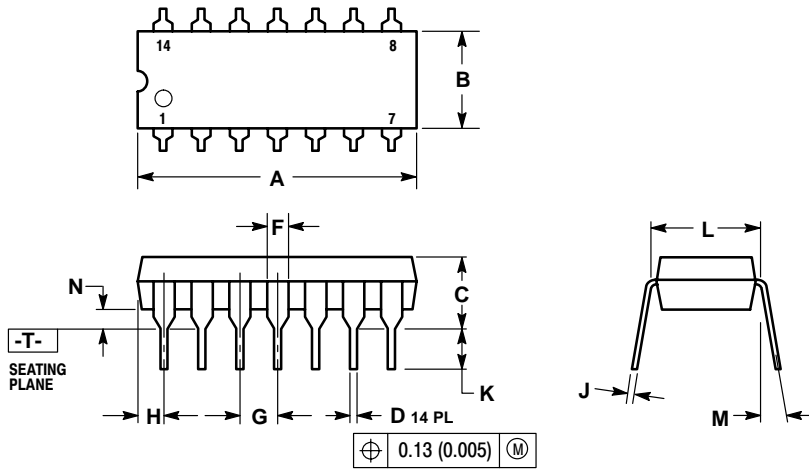
\*Includes all probe and jig capacitance.

Figure 4. Test Circuit

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## PACKAGE DIMENSIONS

PDIP-14  
N SUFFIX  
CASE 646-06  
ISSUE M

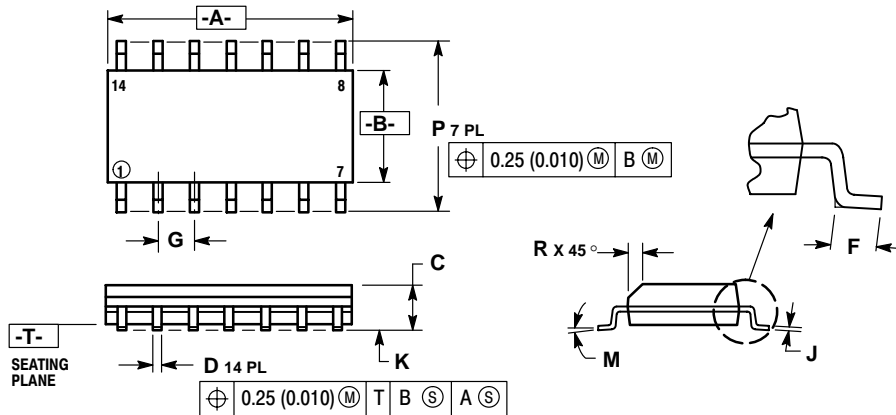


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	18.80
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC 2.54 BSC			
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

SOIC-14  
D SUFFIX  
CASE 751A-03  
ISSUE F



NOTES:

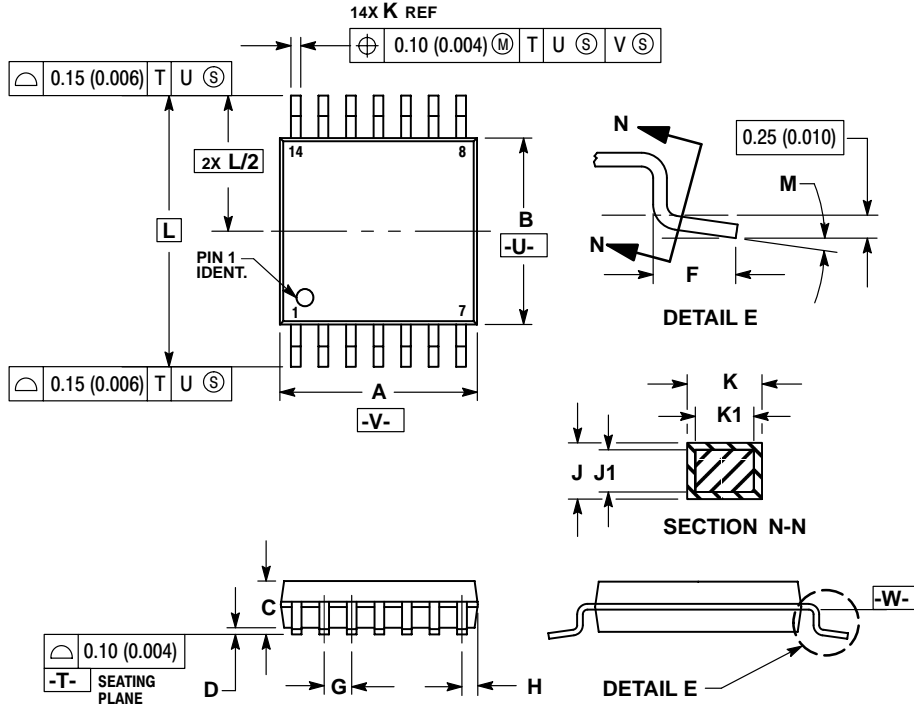
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC 0.050 BSC			
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

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## PACKAGE DIMENSIONS

TSSOP-14  
DT SUFFIX  
CASE 948G-01  
ISSUE O

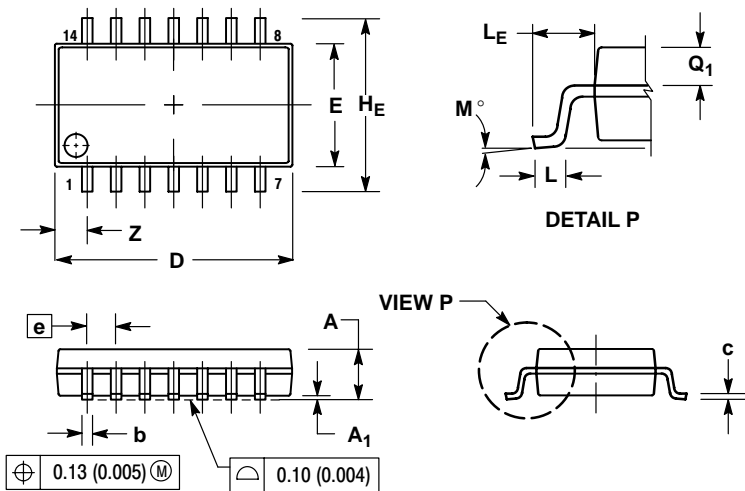


### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°		8°	

SO EIAJ-14  
F SUFFIX  
CASE 965-01  
ISSUE O



### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°		10°	
Q1	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

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